次世代PKG基板用の高信頼性穴埋めインキ！

High–Reliability Hole Plugging Ink for PKG Substrate of Next Generation

熱硬化型穴埋めインキ THP-100 DX Series

Thermal Cure Hole Plugging Ink

特　長　Features

- **高Tg/低CTE**
  High Tg/Low CTE
- **リフロー耐性良好**
  Excellent anti crack resistance at reflow
- **TCT耐性良好**
  Excellent anti crack resistance at TCT
  -65deg.C⇔150deg.C /1000cycle/No crack

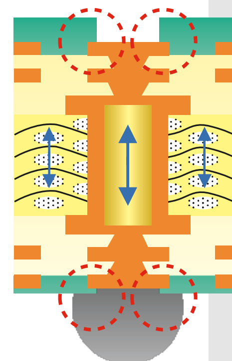
特　性　Properties

	従来品 Conventional product	THP-100 DX7 Mass-produced	THP-100 DX9 Development Product	Test Condition
粘度(dPa·s)	450±50	450±50	350±50	コーンプレート型粘度計 Cone plate type viscometer
ガラス転移温度(deg.C) Tg	150-160	165-175	175-185	TMA (Pulling mode) X-Y方向　X-Y direction
線膨張係数(ppm)　CTE(α1/α2)	30-35／100-110	20-25／55-65	10-15／40-50	

	従来品 Conventional product	THP-100 DX7
Before Reflow		
L2a (C-120/60/60) ＋Reflow (270deg.C/5cycles)		

穴埋めインキの熱膨張により、銅の膨れが発生
Copper swelling occurs due to thermal expansion of hole plugging ink

① Core T=0.4mmPTH=0.25mm
② Treatment
L2a(C120/60/60)
+Reflow(270deg.C /5cycles)
※基板表面実温度



用　途　Application

- **THP-100 DX7：現行PKG、通信、車載基板**
  PKG Substrate, Server, Automotive
- **THP-100 DX9：次世代PKG基板**
  PKG Substrate of Next Generation
- **厚銅回路基板への充填性·低反り性に優れたTHP-100 Z2GFもラインナップ**
  Excellent fillability and low warpage suitable for Thick Copper Circuit boards 'THP-100 Z2GF'